

What is claimed is:

6. (New) A distributor for distributing a flow of liquid over a surface to be cooled, the distributor comprising:

an inlet manifold;

an outlet manifold; and

at least one flow cell connected between the manifolds, the flow cell

comprising:

a cell inlet in fluid communication with the inlet manifold;

a cell outlet in fluid communication with the outlet manifold;

a main flow channel formed by wall segments extending from a base to the surface to be cooled and as a meandering sequence of channel segments for guiding a main flow of liquid from the cell inlet along the surface to the cell outlet with a plurality of changes in the direction of the main flow; and

a bypass flow channel formed by gaps between the wall segments and the surface to be cooled for allowing a bypass flow of liquid from the cell inlet to the cell outlet; wherein

the bypass flow channel interconnects the channel segments of the main flow channel.

7. (New) The distributor as in claim 6 wherein a plurality of flow cells is interconnected between the manifolds, and wherein each of the flow cells comprises a bypass flow channel.

8. (New) The liquid-coolable unit for removing heat from a heat source, the unit comprising a plate heated by the heat source and a distributor as claimed in claim 6 for distributing a flow of cooling liquid over a surface of the plate.

9. (New) The liquid-coolable electronic unit, the unit comprising an electronic circuit encapsulated in a circuit module having an outer surface, and a distributor as claimed in claim 6 for distributing a flow of cooling liquid over the surface.